

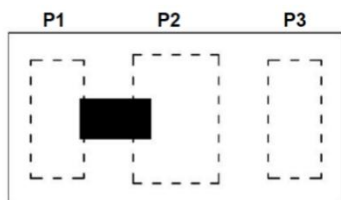
Features

- Multilayer monolithic construction yields high reliability
- Low insertion loss and small size SMD chip design
- Can simplify your complex tuning and circuit design
- LTCC process

Specifications

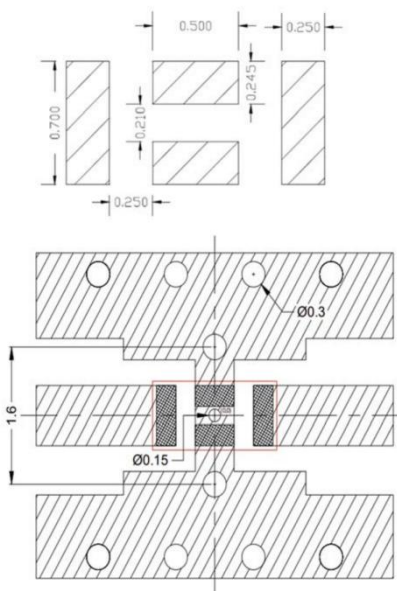
NO.	Parameter	Frequency (MHz)	SPEC	
			Min.	Max.
1	Insertion Loss (dB)	5150~5950		0.85
2	Return Loss (dB)	5150~5950	10	
3	Attenuation (dB)	30~2700	35	
		3400~3800	30	
		7250~7800	15	
		10300~11700	20	
4	In/Output Impedance (Ω)		50	
5	Input Power		0.5W	

Construction



PIN	Connection
1	Input port
2	GND
3	Output port

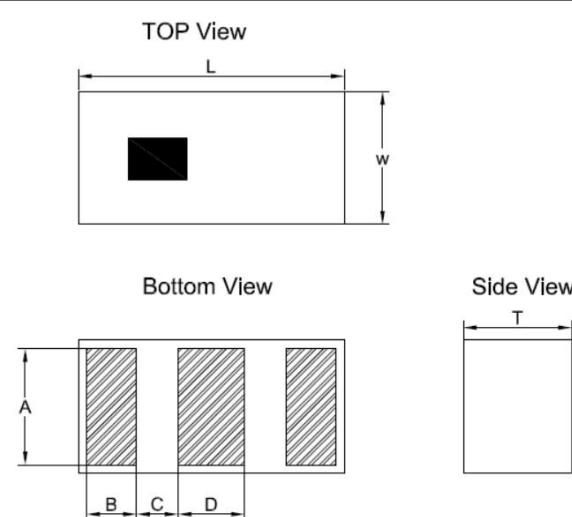
Mounting Considerations



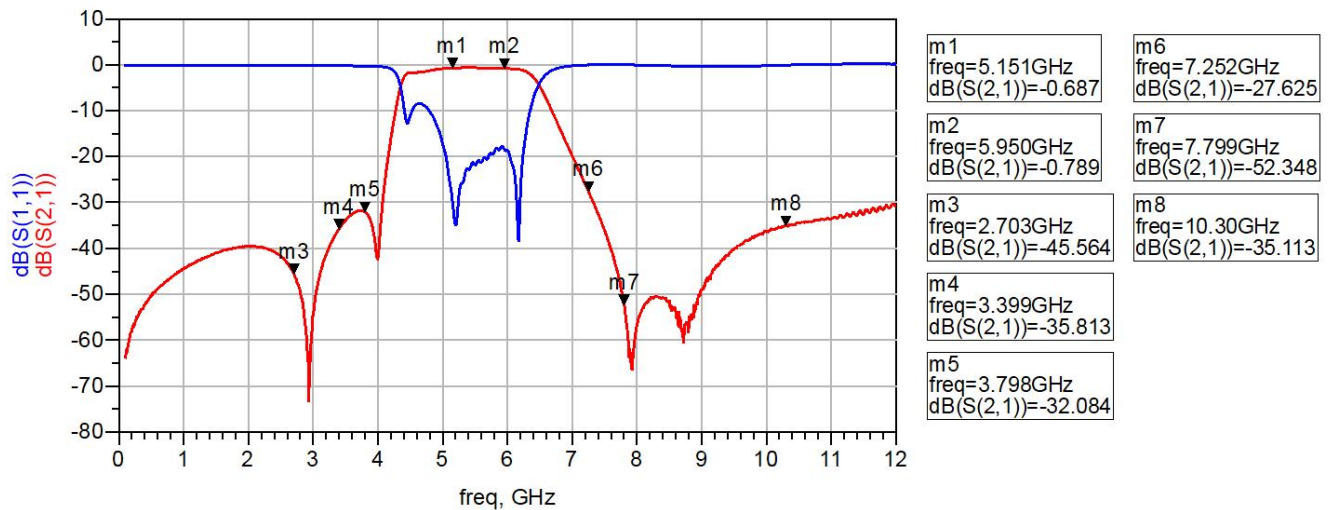
Unit: mm

Line width to be designed to match 50 Ω characteristic impedance, depending on PCB material and thickness

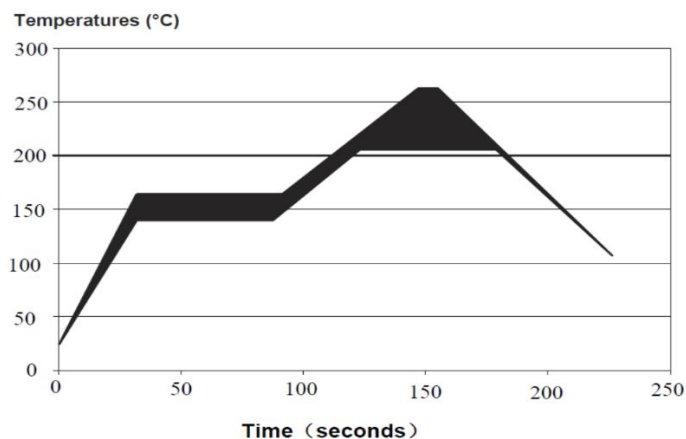
Dimensions

Figure	Symbol	Dimension (mm)
	L	1.60±0.20
	W	0.80±0.20
	T	0.60±0.10
	A	0.70±0.10
	B	0.30±0.10
	C	0.25±0.10
	D	0.4±0.10

Typical Electrical Characteristics (T=25°C)



Solder Reflow Standard Conditioning



Storage Conditions

Temperature : +5 to +30 °C

Humidity : 20 to 70% RH

Term of storage : Within 12 months (After the delivery) *

Baking : Unnecessary

* After peeling off cover tape, do not keep exposing the products to the open air. For the products stored longer than 12 months, confirm their terminals and solderability before use.